

# SOT706-1

plastic thermal enhanced ball grid array package; 552 balls;  
body 37.5 x 37.5 x 1.42 mm; heatsink

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HBGA552
<b>Package type industry code</b>	HBGA552
<b>Package style descriptive code</b>	HBGA (thermal enhanced ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	13-11-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	37.3	-	37.5	37.7	mm
E	package width	37.3	-	37.5	37.7	mm
A	seated height	[tbd]	-	2.15	2.15	mm
A <sub>2</sub>	package height	1.35	-	1.42	1.5	mm
n <sub>2</sub>	actual quantity of termination	-	-	552	-	



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## 2. Package outline

HBGA552: plastic thermal enhanced ball grid array package; 552 balls;  
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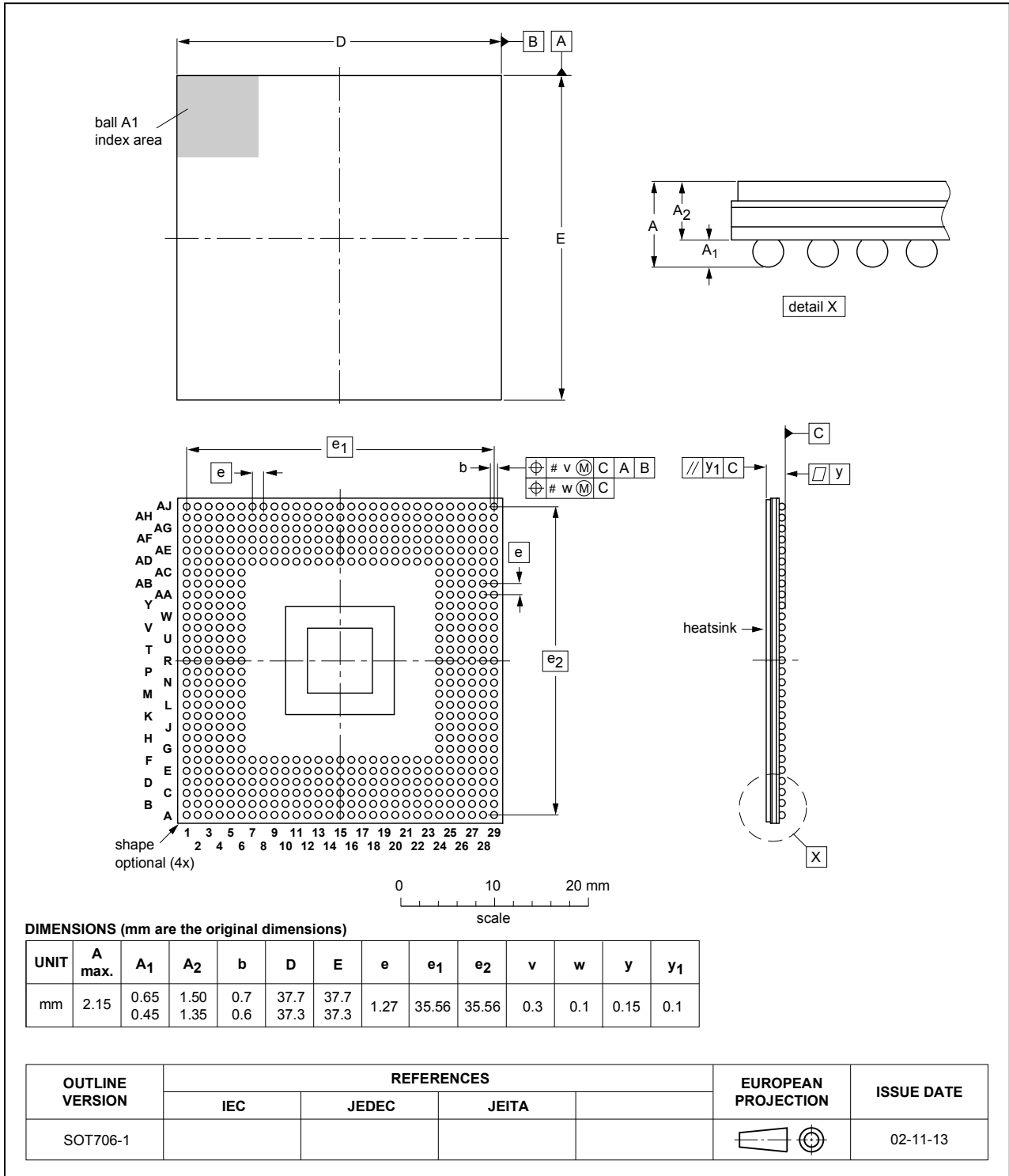


Fig. 1. Package outline HBGA552 (SOT706-1)

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### 3. Legal information

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Date of release: 8 February 2016

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